

Abstract

In the present invention there is formed a sheet-like board member 50 having conductive coating films, such as first pads 55 and die pads 59, formed thereon or a sheet-like board member 50 which has been half-etched by using conductive coating films such as first pads 55 and die pads 59. A hybrid IC can be manufactured by means of utilization of post-processing processes of a semiconductor manufacturer. Further, a hybrid IC can be manufactured without adoption of a support board, and hence there can be manufactured a hybrid IC which is of lower profile and has superior heat dissipation characteristics.